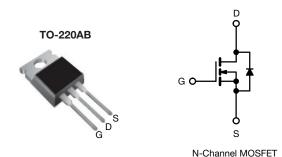
Vishay Siliconix

COMPLIANT

HALOGEN

**FREE** 

# **E Series Power MOSFET**



PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.208		
Q <sub>g</sub> max. (nC)	29			
Q <sub>gs</sub> (nC)	8			
Q <sub>gd</sub> (nC)	7			
Configuration	Single			

### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

### **APPLICATIONS**

- · Server and telecom power supplies
- · Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP240N65E-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	650	V	
Gate-source voltage	$V_{GS}$	± 30	V		
Continuous drain current (T <sub>J</sub> = 150 °C)	$V_{GS}$ at 10 V $T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$	- I <sub>D</sub>	16	А	
	$V_{GS}$ at 10 V $T_C = 100 ^{\circ}C$		10		
Pulsed drain current <sup>a</sup>	I <sub>DM</sub>	33			
Linear derating factor			1.2	W/°C	
Single pulse avalanche energy b		E <sub>AS</sub>	36	mJ	
Maximum power dissipation		$P_{D}$	147	W	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope		dv/dt	100	V/ns	
Reverse diode dv/dt <sup>c</sup>			20	V/115	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 1.6 A
- c.  $I_{SD} \leq I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.6	C/ VV

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		650	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.65	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \mu A$		-	5.0	V
Oale and sealed and	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage		,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zana mata walta sa aluaisa awanant		V <sub>DS</sub> =	650 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 520 V	V <sub>DS</sub> = 520 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 7 A	-	0.208	0.240	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 7 A		-	1	-	S
Dynamic		•		•		•	
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$ ,		-	960	-	
Output capacitance	C <sub>oss</sub>	,	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$		40	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 100 kHz		-	2	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>			-	42	-	pF -
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>	$V_{DS} = 0$	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$		273	-	
Total gate charge	Qg			-	19	29	nC
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 7 A, V_{DS} = 520 V$	-	8	-	
Gate-drain charge	Q <sub>gd</sub>				7	-	1
Turn-on delay time	t <sub>d(on)</sub>		V <sub>DD</sub> = 520 V, I <sub>D</sub> = 7 A,		16	32	
Rise time	t <sub>r</sub>	V <sub>DD</sub> :			20	40	
Turn-off delay time	t <sub>d(off)</sub>		$= 10 \text{ V}, \text{ R}_{\text{g}} = 9.1 \Omega$	-	25	50	ns
Fall time	t <sub>f</sub>			-	12	24	
Gate input resistance	$R_g$	f = 1 MHz, Open Drain		0.3	0.7	1.4	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	16	
Pulsed diode forward current	I <sub>SM</sub>			-	-	33	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 7 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	-			269	538	ns
Reverse recovery charge	Q <sub>rr</sub>	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 7 \text{A},$ di/dt = 100 A/µs, $V_R = 25 \text{V}$		-	2.7	5.4	μC
Reverse recovery current	I <sub>RRM</sub>			_	17	-	A



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

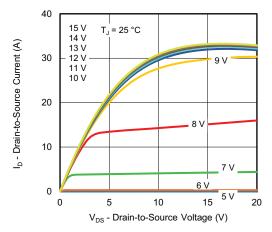


Fig. 1 - Typical Output Characteristics

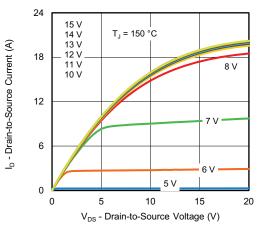


Fig. 2 - Typical Output Characteristics

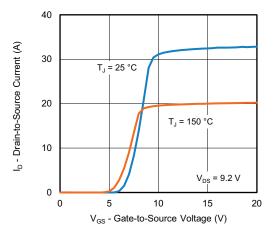


Fig. 3 - Typical Transfer Characteristics

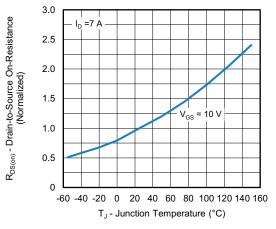


Fig. 4 - Normalized On-Resistance vs. Temperature

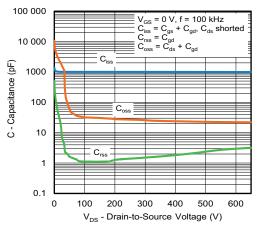


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

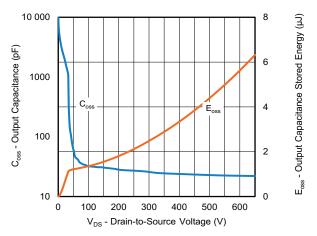


Fig. 6 - Coss and Eoss vs. VDS



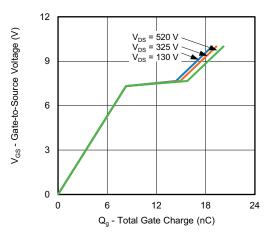


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

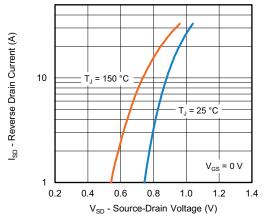


Fig. 8 - Typical Source-Drain Diode Forward Voltage

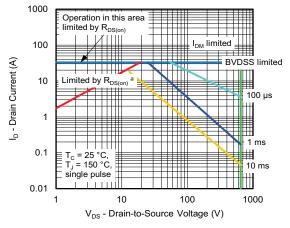


Fig. 9 - Maximum Safe Operating Area



a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

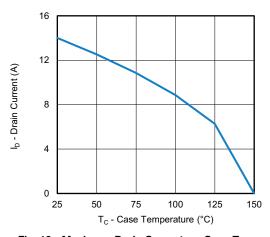


Fig. 10 - Maximum Drain Current vs. Case Temperature

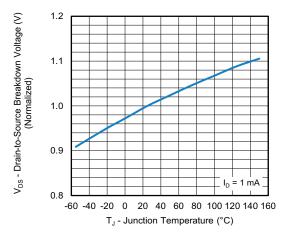


Fig. 11 - Temperature vs. Drain-to-Source Voltage



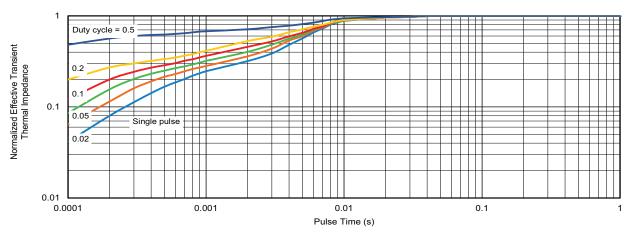


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

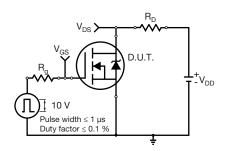


Fig. 13 - Switching Time Test Circuit

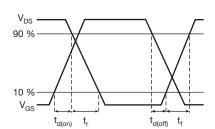


Fig. 14 - Switching Time Waveforms

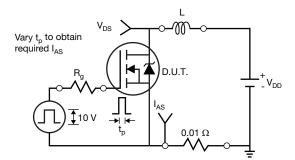


Fig. 15 - Unclamped Inductive Test Circuit

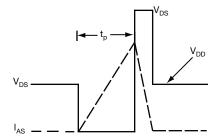


Fig. 16 - Unclamped Inductive Waveforms

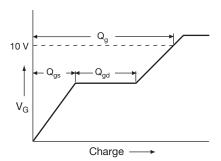


Fig. 17 - Basic Gate Charge Waveform

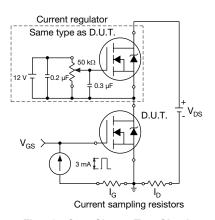
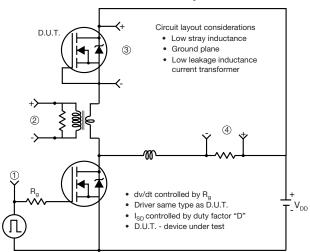


Fig. 18 - Gate Charge Test Circuit



### Peak Diode Recovery dv/dt Test Circuit



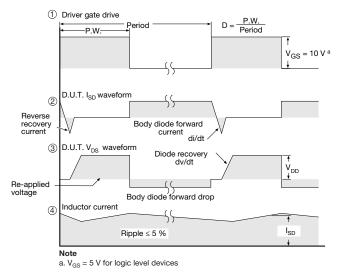


Fig. 19 - For N-Channel

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